

### Lead-Free & RoHs Compliance!!

## **SPECIFICATION FOR APPROVAL**

CUSTOMER	•
	•

CUSTOMER P/N :

OUR DWG No:

QUANTITY :

Pcs. DATE:

ITEM :

0

PBY201209T-221Y-N

2013/05/24

	<u> </u>	FICATION PTED BY:				
COMPONENT						
ENGINEER						
ELECTRICAL						
ENGINEER						
MECHANICAL						
ENGINEER						
APPROVED						
REJECTED						
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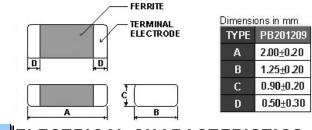
# **PBY201209T Series Specification**

<b>1</b> Scope: This s	pecification applies to MULTILAYER FE	RRITE CHIP BEADS
	ing: Product Identification	Style 5 code e
3 Rating:		
Operating T	emperature: $-55$ °C $\sim$ $125$ °C (Incl	uding self - temperature rise)
operating i		danig sen - temperature rise)
	emperature: $-55^\circ \mathbb{C} \sim 125^\circ \mathbb{C}$ (at	ter PCB)
	emperature: $-55^\circ \mathbb{C} \sim 125^\circ \mathbb{C}$ (at	
Storage T	demperature: $-55^{\circ}$ C $\sim 125^{\circ}$ C(at $-5^{\circ}$ C $\sim 40^{\circ}$ C,Humidi	ter PCB)
Storage T	remperature: -55°C~125°C(af -5°C~40°C,Humidi	ter PCB)
Storage T    4   Marking:   No Marking   5	emperature: -55℃~125℃(af -5℃~40℃,Humidi	In case of doubt
Storage T <u>4</u> Marking: No Markin	emperature: -55℃~125℃(af -5℃~40℃,Humidi	ter PCB) ty 40%~70%(before PCB)



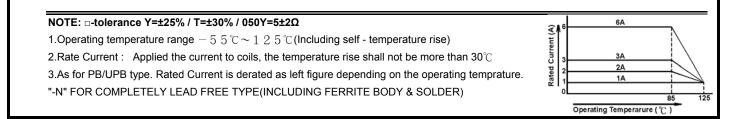
## **PBY201209T Series Specification**

### 6 Configuration and Dimensions:



### 7 ELECTRICAL CHARACTERISTICS :

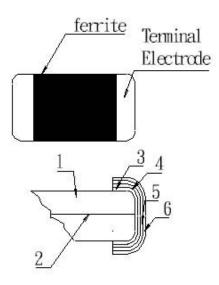
				Rated
Part No.	Impedance	Test Freq.	RDC	Current
	(Ω)		(Ω)Max.	(mA)Max.
PBY201209T-100□-N	10	100 MHz,200 mV	0.01	6000
PBY201209T-170□-N	17	100 MHz,200 mV	0.02	5000
PBY201209T-300□-N	30	100 MHz,200 mV	0.015	4000
PBY201209T-500□-N	50	100 MHz,200 mV	0.025	3000
PBY201209T-600□-N	60	100 MHz,200 mV	0.03	3000
PBY201209T-800□-N	80	100 MHz,200 mV	0.04	3000
PBY201209T-121□-N	120	100 MHz,200 mV	0.04	3000
PBY201209T-221□-N	220	100 MHz,200 mV	0.08	2000
PBY201209T-301□-N	300	100 MHz,200 mV	0.08	2000
PBY201209T-471□-N	470	100 MHz,200 mV	0.1	2000
PBY201209T-601□-N	600	100 MHz,200 mV	0.1	2000
PBY201209T-751□-N	750	100 MHz,200 mV	0.12	1500
PBY201209T-102 - N	1000	100 MHz,200 mV	0.12	1500
PBY201209T-152□-N	1500	100 MHz,200 mV	0.3	1000





## **PBY201209T Series Specification**





#### 8.2 Material List:

NO	PART	MATERIAL				
1	Ferrite Substance	NiO-CuO-ZnO-Ferrite				
2	Silver electrode	Ag				
3	Silver electrode	lectrode Ag				
4	Cu plating	Cu				
5	Ni plating	Ni				
6	Sn plating	Sn				



# PBY201209T Series Specification

### 9 Reliability Of Ferrite Multilayer Chip Bead

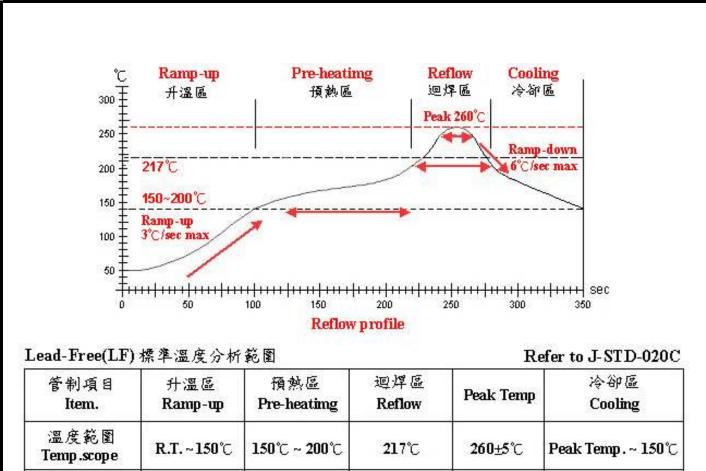
No	Item Specification Test Method						
-1-1	Flexure Strength	The forces applied on the right	Test d	evice shall be soldered on the substrate	Э		
		conditions must not damage	Substr	ate Dimension: 100x40x1.6mm			
		the terminal electrode and the	Deflec	tion: 2.0mm	) 		
		ferrite	Keepir	ng Time: 30sec			
			*For 1	00505, substrate dimension is 100x40x	0.8mm		
-1-2	Vibration		Test d	evice shall be soldered on the substrate	9		
			Oscilla	ation Frequency: 10 to 55 to 10Hz for 1r	nin		
				ude: 1.5mm			
			Time:	2hrs for each axis (X, Y & Z), total 6hrs			
-1-3	Resistance to Soldering Heat	Appearance: No damage		eating: 150°C, 1min			
	_	More than 75% of the terminal Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)					
		electrode should be covered	Solder Temperature: 260±5°C				
		with solder.	Immersion Time: 10±1sec				
		Impedance : within ±30% of					
		initial value					
-1-4	Solder ability	The electrodes shall be at	at Pre-heating: 150°C, 1min				
		least 95% covered with new	Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)				
		solder coating Solder Temperature: 245±5°C (Pb-Free)					
			Immer	sion Time: 4±1sec			
-1-5	Terminal Strength Test	No split termination	Test d	evice shall be soldered on the substrate	Э,		
		Chip	then a	pply a force in the direction of the arrow	Ι.		
		F	Force	: 5N			
			Keepir	ng Time: 10±1sec			
		Mounting Pad					
	nvironmental Performanc						
No	Item	Specification	Test Method				
-2-1	Temperature Cycle	Appearance: No damage	One c		Time (main		
		Impedance: within±30% of	Step	Temperature (°C)	Time (min		
		initial value	1	-55±3	30		
			2	25±2	3		
			3	125±3	30		

		4	25±2	3	
		Total: 100cycles			
		Measured after exposure in the room condition for 24hrs			
1-2-2	Humidity Resistance	Tempe	erature: 40±2°C		
		Relative Humidity: 90 ~ 95% / Time: 1000hrs			
		Measured after exposure in the room condition for 24hrs			
1-2-3	High	Temperature: 125±3℃ / Relative Humidity: 0%			
	Temperature Resistance	Applied Current: Rated Current /Time: 1000hrs			
		Measured after exposure in the room condition for 24hrs			
1-2-4	Low	Temperature: -55±3℃			
	Temperature Resistance	Relative Humidity: 0% / Time: 1000hrs			
		Measured after exposure in the room condition for 24hrs			



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標準時間 Time spec.	1000	60 ~ 180 sec	60 ~ 150sec	20 ~ 40 sec	la <del>rra</del> n
實際時間 Time result	100	75 ~ 100 sec	90 ~ 120 sec	20 ~ 35 sec	2 <del></del>

NOTE :

1. Re-flow possible times : within 2 times

2. Nitrogen adopted is recommended while in re-flow

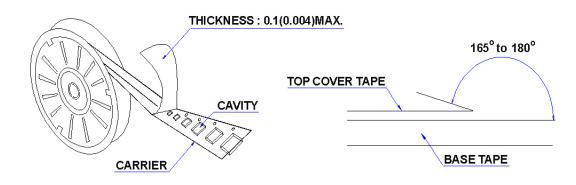


## **PBY201209T Series Specification**

### 11 PACKAGING

#### 11.1 Packaging -Cover tape

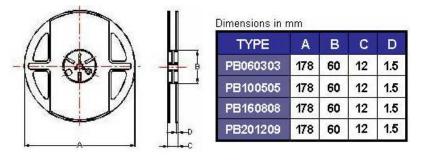
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



#### **11.2 Packaging Quantity**

TYPE	BULK	PCS/REEL
PB060303	*	15000
PB100505	*	10000
PB160808	*	4000
PB201209	*	4000

#### **11.3 Reel Dimensions**



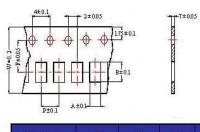


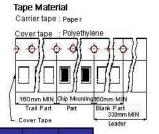
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## **PBY201209T Series Specification**

### 11 PACKAGING

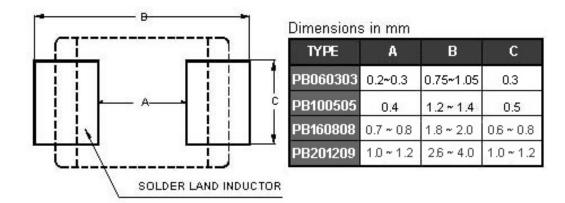
#### 11.4 Tape Dimensions in mm





TYPE	Α	В	Ī	W	P	F
PB060303	0.38	0.67	0.45	8	2	3.5
PB100505	0.65	1.15	0.60	8	2	3.5
PB160808	1.05	1.85	0.95	8	4	3.5
PB201209	1.50	2.30	0.97	8	4	3.5

### 12 Recommended Pattern



### 13 Note:

- 1. Please make sure that your product is has been evaluated and confirmed against your specifications when our product is mounted to your product.
- 2. Do not knock nor drop.
- 3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose, under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
- 4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)